

# 74AHC573; 74AHCT573

Octal D-type transparent latch; 3-state

Rev. 7 — 8 November 2011

Product data sheet

## 1. General description

The 74AHC573; 74AHCT573 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74AHC573; 74AHCT573 consists of eight D-type transparent latches featuring separate D-type inputs for each latch and 3-state true outputs for bus oriented applications. A latch enable input (LE) and an output enable input ( $\overline{OE}$ ) are common to all latches.

When pin LE is HIGH, data at the Dn inputs enters the latches. In this condition the latches are transparent, i.e. a latch output will change state each time its corresponding Dn input changes. When pin LE is LOW, the latches store the information that is present at the Dn inputs, after a set-up time preceding the HIGH-to-LOW transition of LE.

When pin  $\overline{OE}$  is LOW, the contents of the 8 latches are available at the outputs. When pin  $\overline{OE}$  is HIGH, the outputs go to the high-impedance OFF-state. Operation of the  $\overline{OE}$  input does not affect the state of the latches.

The 74AHC573; 74AHCT573 is functionally identical to the 74AHC373; 74AHCT373, but has a different pin arrangement.

## 2. Features and benefits

- Balanced propagation delays
- All inputs have a Schmitt trigger action
- Common 3-state output enable input
- Functionally identical to the 74AHC373; 74AHCT373
- Inputs accept voltages higher than  $V_{CC}$
- Input levels:
  - ◆ For 74AHC573: CMOS input level
  - ◆ For 74AHCT573: TTL input level
- ESD protection:
  - ◆ HBM EIA/JESD22-A114E exceeds 2000 V
  - ◆ MM EIA/JESD22-A115-A exceeds 200 V
  - ◆ CDM EIA/JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
<b>74AHC573</b>				
74AHC573D	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHC573PW	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHC573BQ	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
<b>74AHCT573</b>				
74AHCT573D	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHCT573PW	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHCT573BQ	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

### 4. Functional diagram

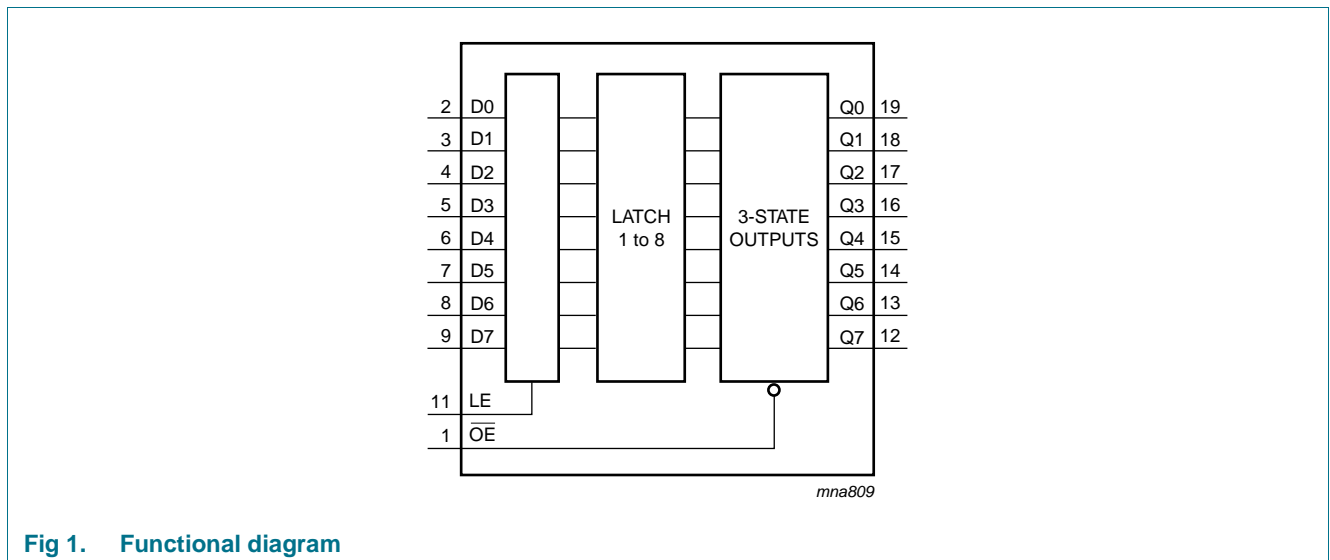


Fig 1. Functional diagram

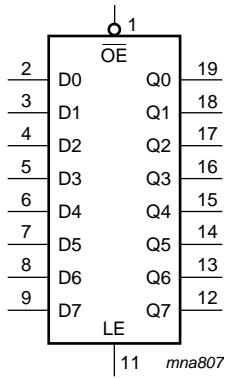


Fig 2. Logic symbol

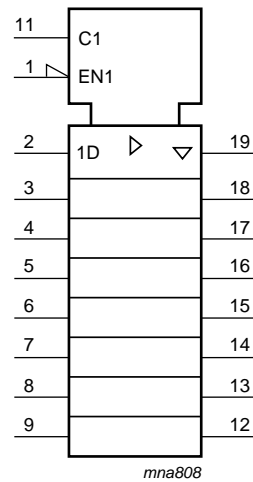


Fig 3. IEC logic symbol

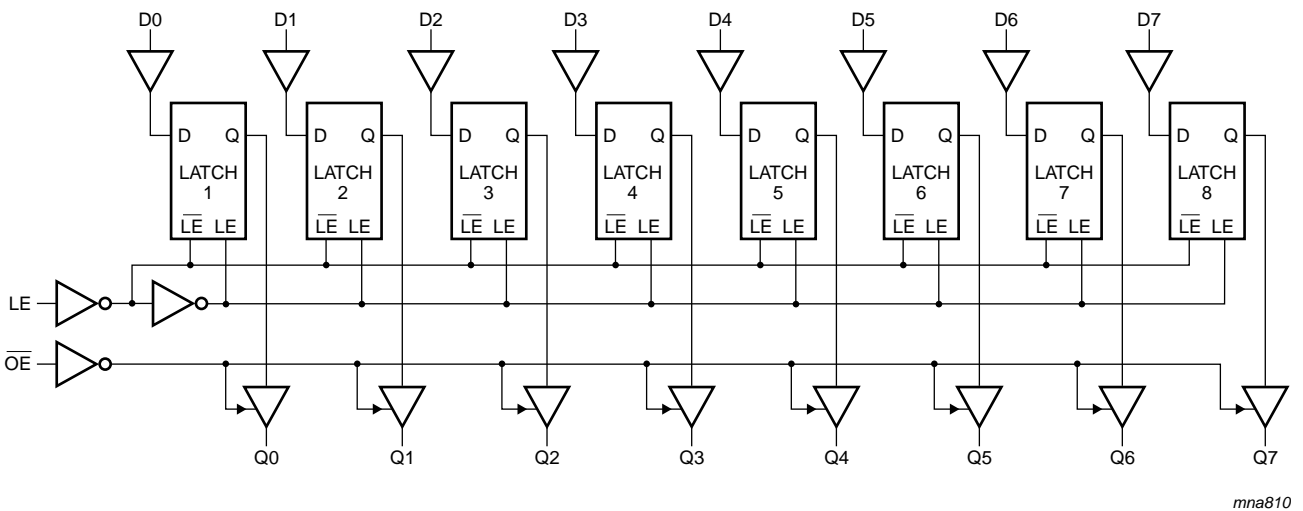
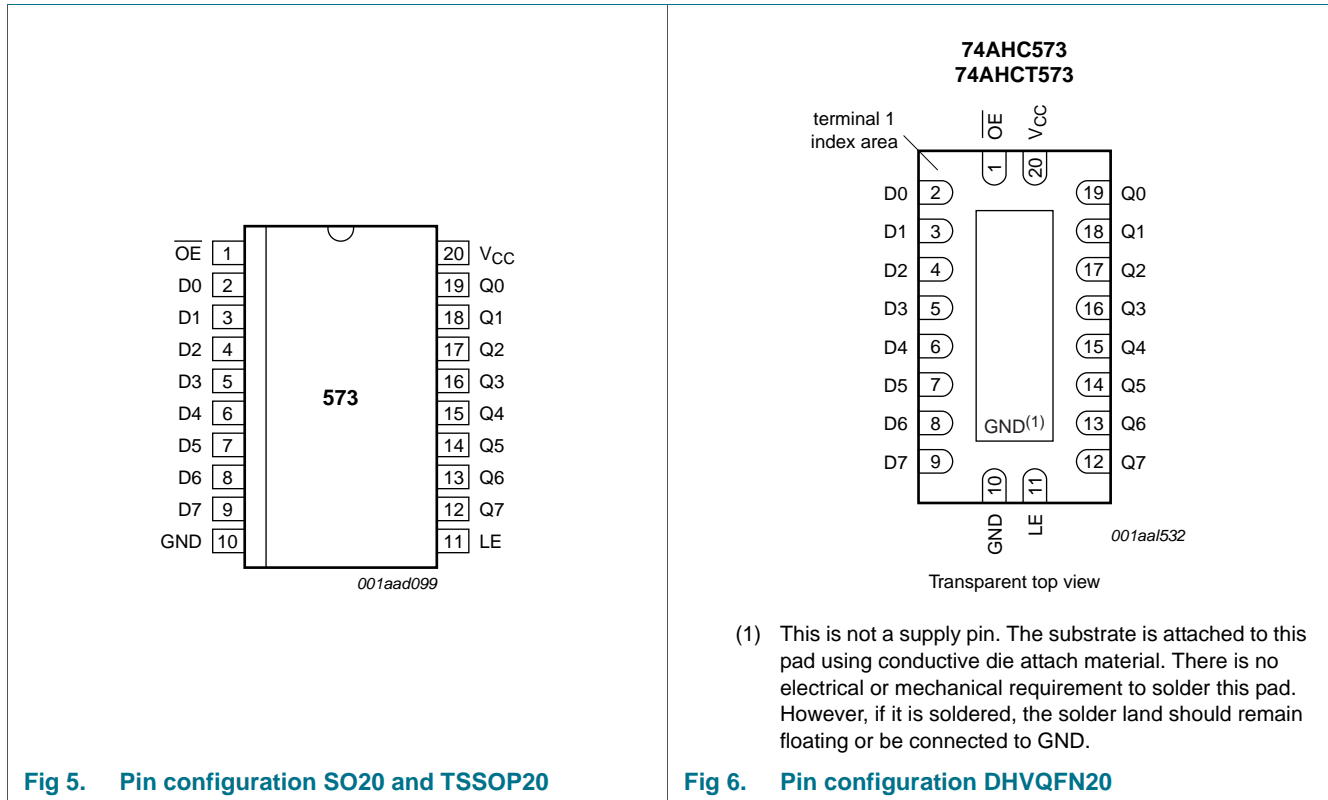


Fig 4. Logic diagram

## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}$	1	output enable input (active LOW)
D0 to D7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
LE	11	latch enable (active HIGH)
Q0 to Q7	19, 18, 17, 16, 15, 14, 13, 12	data output
V <sub>CC</sub>	20	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Operating mode	Input			Internal latch	Output Qn
	OE	LE	Dn		
Enable and read register (transparent mode)	L	H	L	L	L
			H	H	H
Latch and read register	L	L	l	L	L
			h	H	H
Latch register and disable outputs	H	L	l	L	Z
			h	H	Z

- [1] H = HIGH voltage level;  
 h = HIGH voltage level one set-up time prior to the HIGH-to-LOW LE transition;  
 L = LOW voltage level;  
 l = LOW voltage level one set-up time prior to the HIGH-to-LOW LE transition;  
 Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	[1] -20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -20	+20	mA
$I_O$	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5)$ V	-25	+25	mA
$I_{CC}$	supply current		-	+75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to $+125$ °C	[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- [2] For SO20 packages: above 70 °C the value of  $P_{tot}$  derates linearly at 8 mW/K.  
 For TSSOP20 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 5.5 mW/K.  
 For DHVQFN20 packages: above 60 °C the value of  $P_{tot}$  derates linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>74AHC573</b>						
$V_{CC}$	supply voltage		2.0	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	-	100	ns/V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V
<b>74AHCT573</b>						
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max	Min	Typ	Max	
<b>74AHC573</b>											
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	-	-	1.5	-	1.5	-	-	V
		$V_{CC} = 3.0\text{ V}$	2.1	-	-	2.1	-	2.1	-	-	V
		$V_{CC} = 5.5\text{ V}$	3.85	-	-	3.85	-	3.85	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	-	0.5	-	0.5	-	-	0.5	V
		$V_{CC} = 3.0\text{ V}$	-	-	0.9	-	0.9	-	-	0.9	V
		$V_{CC} = 5.5\text{ V}$	-	-	1.65	-	1.65	-	-	1.65	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$									
		$I_O = -50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	2.9	3.0	-	2.9	-	2.9	-	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	2.58	-	-	2.48	-	2.40	-	-	V
	$I_O = -8.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.94	-	-	3.80	-	3.70	-	-	V	
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$									
		$I_O = 50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	-	0	0.1	-	0.1	-	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	-	0.1	V
		$I_O = 4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.36	-	0.44	-	-	0.55	V
	$I_O = 8.0\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.36	-	0.44	-	-	0.55	V	

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max	Min	Typ	Max	
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.25	-	±2.5	-	-	±10.0	μA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	4.0	-	40	-	-	80	μA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	-	3	10	-	10	-	-	10	pF
C <sub>O</sub>	output capacitance		-	4	-	-	-	-	-	10	pF

### 74AHCT573

V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V									
		I <sub>O</sub> = −50 μA	4.4	4.5	-	4.4	-	4.4	-	-	V
		I <sub>O</sub> = −8.0 mA	3.94	-	-	3.80	-	3.70	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V									
		I <sub>O</sub> = 50 μA	-	0	0.1	-	0.1	-	-	0.1	V
		I <sub>O</sub> = 8.0 mA	-	-	0.36	-	0.44	-	-	0.55	V
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND per input pin; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	-	±0.25	-	±2.5	-	-	±10.0	μA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	4.0	-	40	-	-	80	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> − 2.1 V; I <sub>O</sub> = 0 A; other pins at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	-	1.5	mA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	-	3	10	-	10	-	-	10	pF
C <sub>O</sub>	output capacitance		-	4	-	-	-	-	-	10	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 11](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
<b>74AHC573</b>										
t <sub>pd</sub>	propagation delay	Dn to Qn; see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.5	11.0	1.0	13.0	1.0	14.0	ns
		C <sub>L</sub> = 50 pF	-	7.8	14.5	1.0	16.5	1.0	18.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.9	6.8	1.0	8.0	1.0	8.5	ns
	C <sub>L</sub> = 50 pF	-	5.5	8.8	1.0	10.0	1.0	11.0	ns	
	LE to Qn; see <a href="#">Figure 8</a> <sup>[2]</sup>	V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.8	11.9	1.0	14.0	1.0	15.0	ns
		C <sub>L</sub> = 50 pF	-	8.3	15.4	1.0	17.5	1.0	19.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.2	7.7	1.0	9.0	1.0	10.0	ns
C <sub>L</sub> = 50 pF		-	5.9	9.7	1.0	11.0	1.0	12.5	ns	
t <sub>en</sub>	enable time	OE to Qn; see <a href="#">Figure 9</a> <sup>[3]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.8	11.5	1.0	13.5	1.0	14.5	ns
		C <sub>L</sub> = 50 pF	-	8.3	15.0	1.0	17.0	1.0	19.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.4	7.7	1.0	9.0	1.0	10.0	ns
C <sub>L</sub> = 50 pF	-	6.3	9.7	1.0	11.0	1.0	12.5	ns		
t <sub>dis</sub>	disable time	OE to Qn; see <a href="#">Figure 9</a> <sup>[4]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	6.8	11.0	1.0	13.0	1.0	14.0	ns
		C <sub>L</sub> = 50 pF	-	9.7	14.5	1.0	16.5	1.0	18.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.6	7.7	1.0	9.0	1.0	10.0	ns
C <sub>L</sub> = 50 pF	-	7.4	9.7	1.0	11.0	1.0	12.5	ns		
t <sub>w</sub>	pulse width	LE HIGH; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	5.0	-	-	5.0	-	5.0	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	5.0	-	-	5.0	-	5.0	-	ns
t <sub>su</sub>	set-up time	Dn to LE; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.5	-	-	3.5	-	3.5	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	3.5	-	-	3.5	-	3.5	-	ns



**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 11](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit	
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max		
t <sub>h</sub>	hold time	Dn to LE; see <a href="#">Figure 10</a>									
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.5	-	-	1.5	-	1.5	-	ns	
		V <sub>CC</sub> = 4.5 V to 5.5 V	1.5	-	-	1.5	-	1.5	-	ns	
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>i</sub> = GND to V <sub>CC</sub>	[5]	-	12	-	-	-	-	pF	
<b>74AHCT573; V<sub>CC</sub> = 4.5 V to 5.5 V</b>											
t <sub>pd</sub>	propagation delay	Dn to Qn; see <a href="#">Figure 7</a>	[2]								
		C <sub>L</sub> = 15 pF	-	3.5	5.5	1	6.5	1	7.0	ns	
		C <sub>L</sub> = 50 pF	-	4.9	7.5	1	8.5	1	9.5	ns	
		LE to Qn; see <a href="#">Figure 8</a>	[2]								
		C <sub>L</sub> = 15 pF	-	3.9	6.0	1	7.0	1	7.5	ns	
		C <sub>L</sub> = 50 pF	-	5.5	8.5	1	9.5	1	11.0	ns	
t <sub>en</sub>	enable time	OE to Qn; see <a href="#">Figure 9</a>	[3]								
		C <sub>L</sub> = 15 pF	-	4.1	6.5	1	7.5	1	8.5	ns	
		C <sub>L</sub> = 50 pF	-	5.9	8.5	1	10.0	1	11.0	ns	
t <sub>dis</sub>	disable time	OE to Qn; see <a href="#">Figure 9</a>	[4]								
		C <sub>L</sub> = 15 pF	-	4.5	6.5	1	7.5	1	8.5	ns	
		C <sub>L</sub> = 50 pF	-	6.4	9.0	1	10.0	1	11.5	ns	
t <sub>W</sub>	pulse width	LE HIGH; see <a href="#">Figure 8</a>		5.0	-	-	5.0	-	5.0	-	ns
t <sub>su</sub>	set-up time	Dn to LE; see <a href="#">Figure 10</a>		3.5	-	-	3.5	-	3.5	-	ns
t <sub>h</sub>	hold time	Dn to LE; see <a href="#">Figure 10</a>		1.5	-	-	1.5	-	1.5	-	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>i</sub> = GND to V <sub>CC</sub>	[5]	-	18	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V<sub>CC</sub> = 3.3 V and V<sub>CC</sub> = 5.0 V).

[2] t<sub>pd</sub> is the same as t<sub>PHL</sub> and t<sub>PLH</sub>.

[3] t<sub>en</sub> is the same as t<sub>PZH</sub> and t<sub>PZL</sub>.

[4] t<sub>dis</sub> is the same as t<sub>PHZ</sub> and t<sub>PLZ</sub>.

[5] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

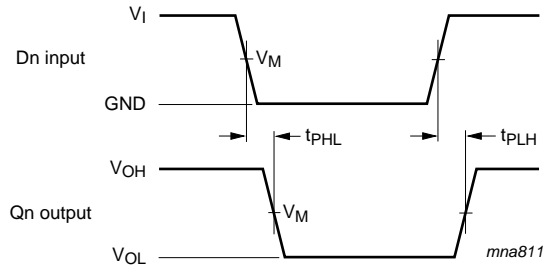
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

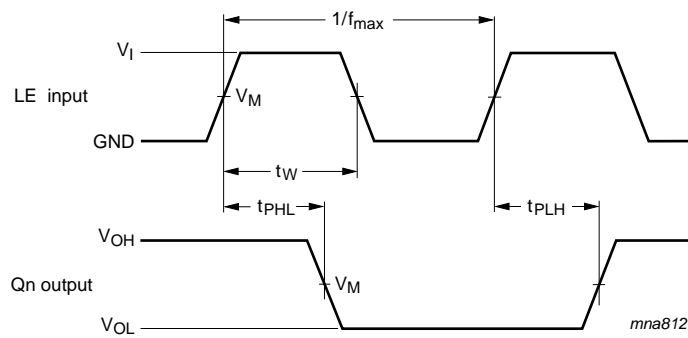
∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

## 11. Waveforms



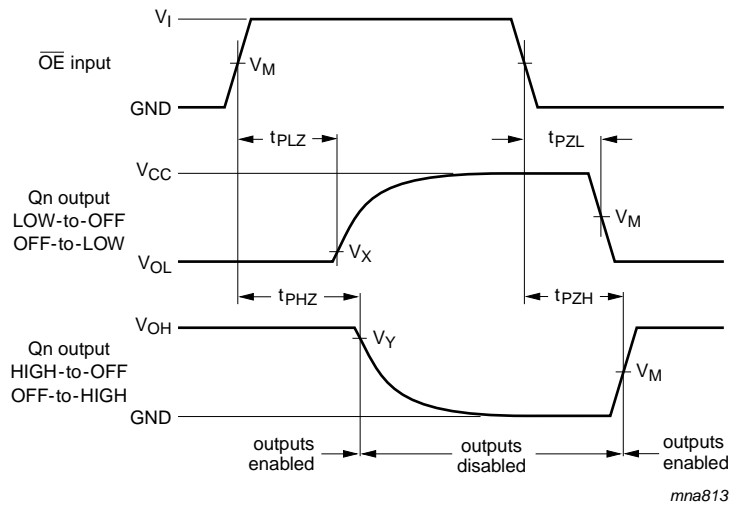
Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. Data input to output propagation delays**



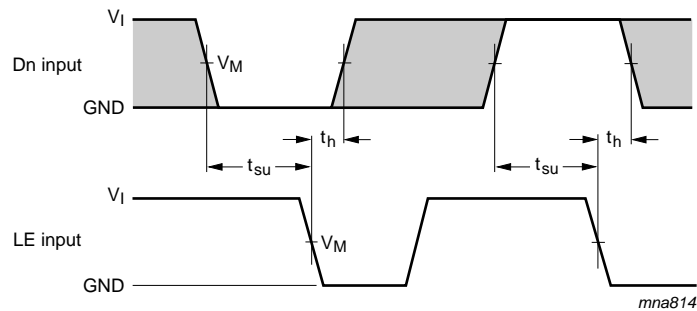
$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. Latch enable input to output propagation delays**



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 9. Enable and disable times**

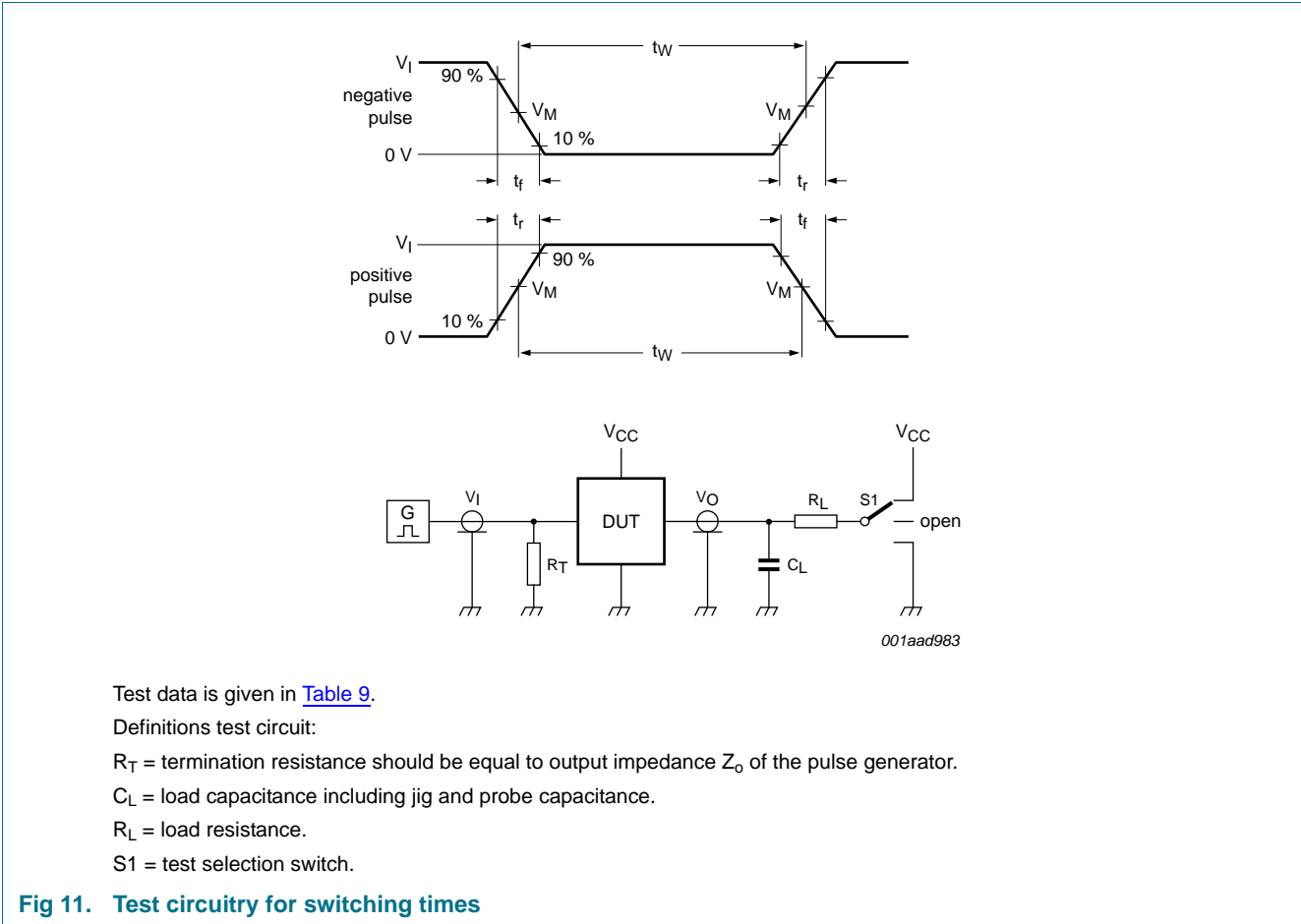


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.  
 The shaded areas indicate when the input is permitted to change for predictable output performance.

**Fig 10. Data set-up and hold times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74AHC573	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
74AHCT573	1.5 V	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

$R_L$  = load resistance.

S1 = test selection switch.

**Fig 11. Test circuitry for switching times**

**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74AHC573	$V_{CC}$	$\leq 3.0$ ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74AHCT573	3.0 V	$\leq 3.0$ ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

## 12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

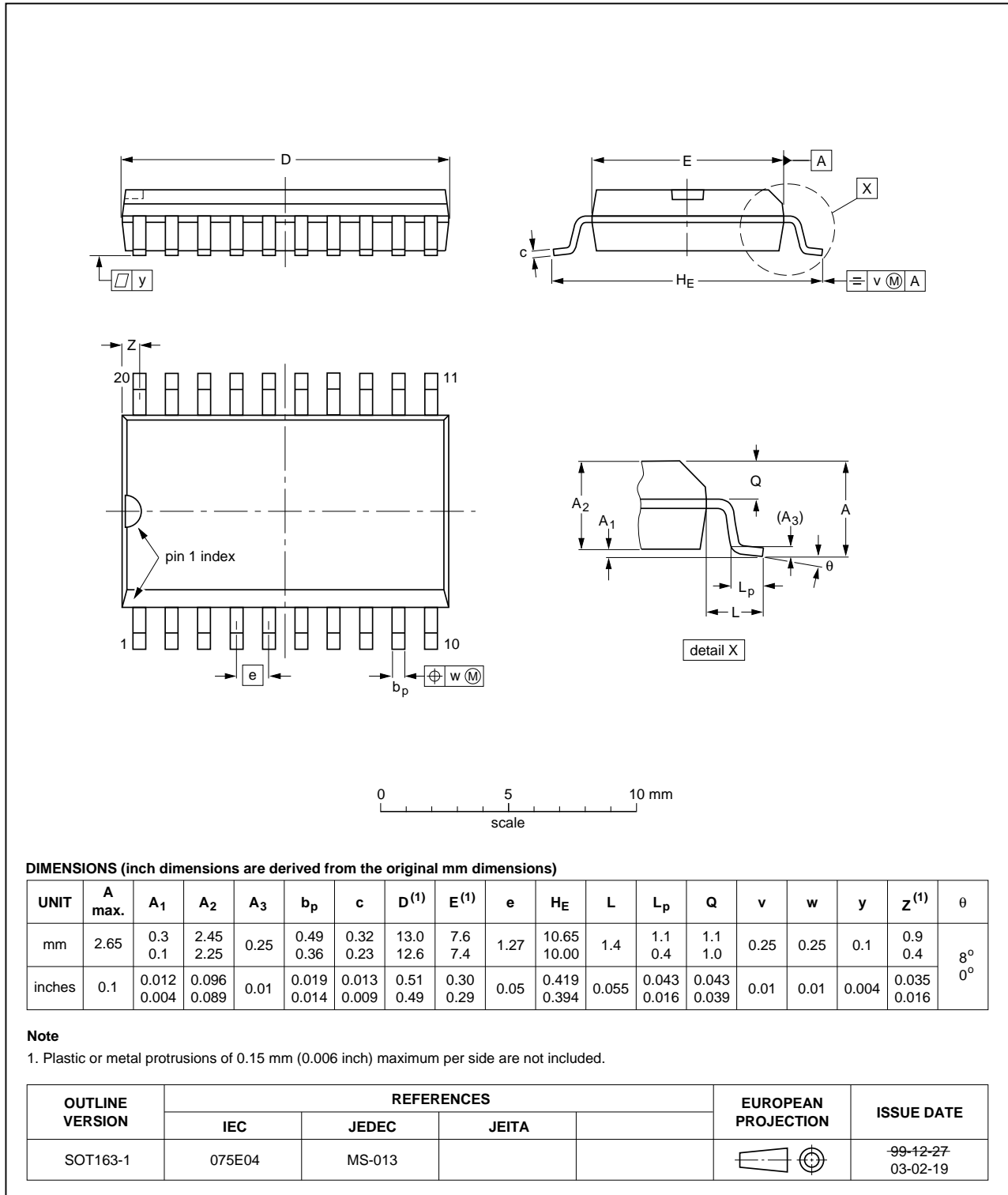


Fig 12. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

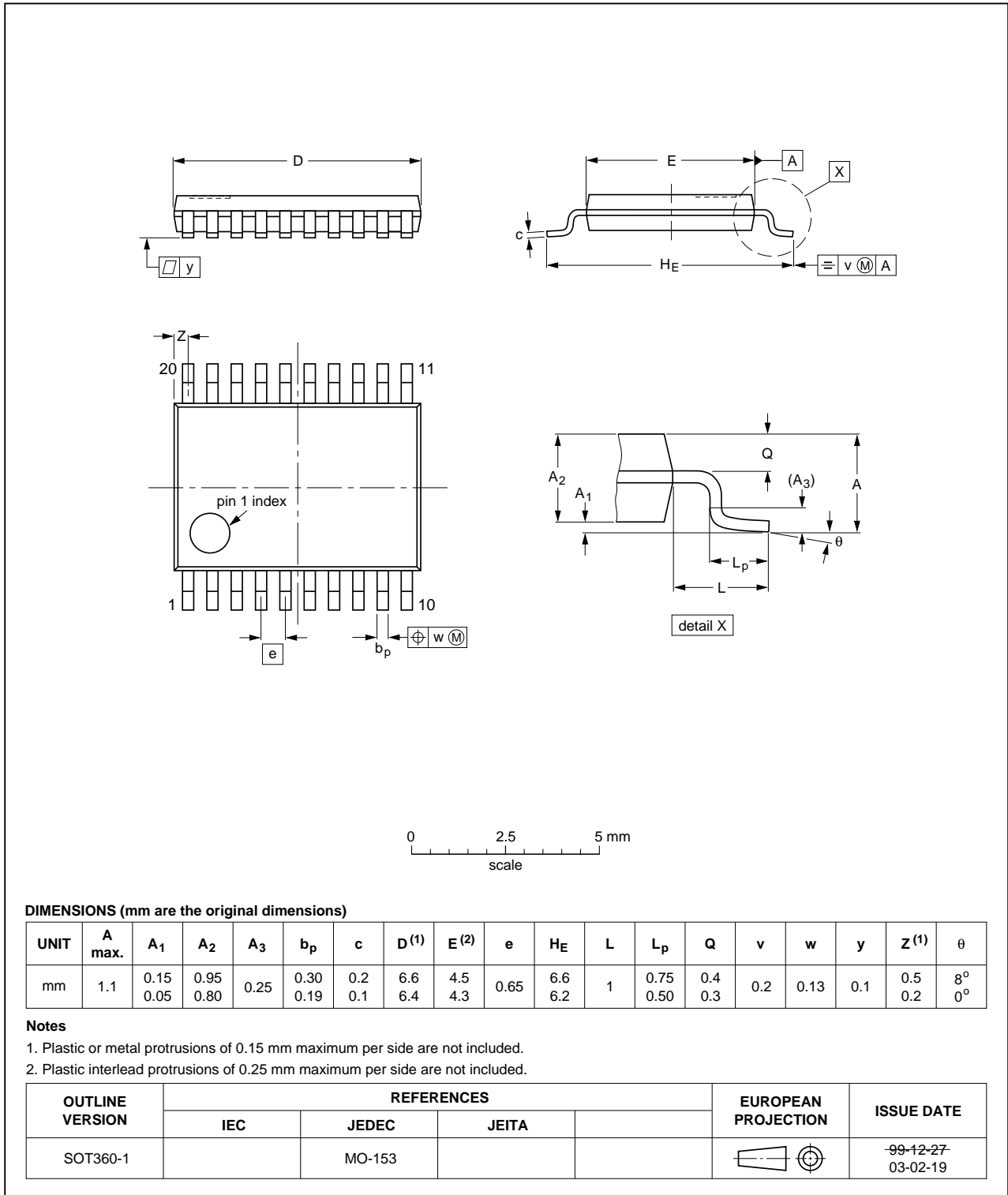
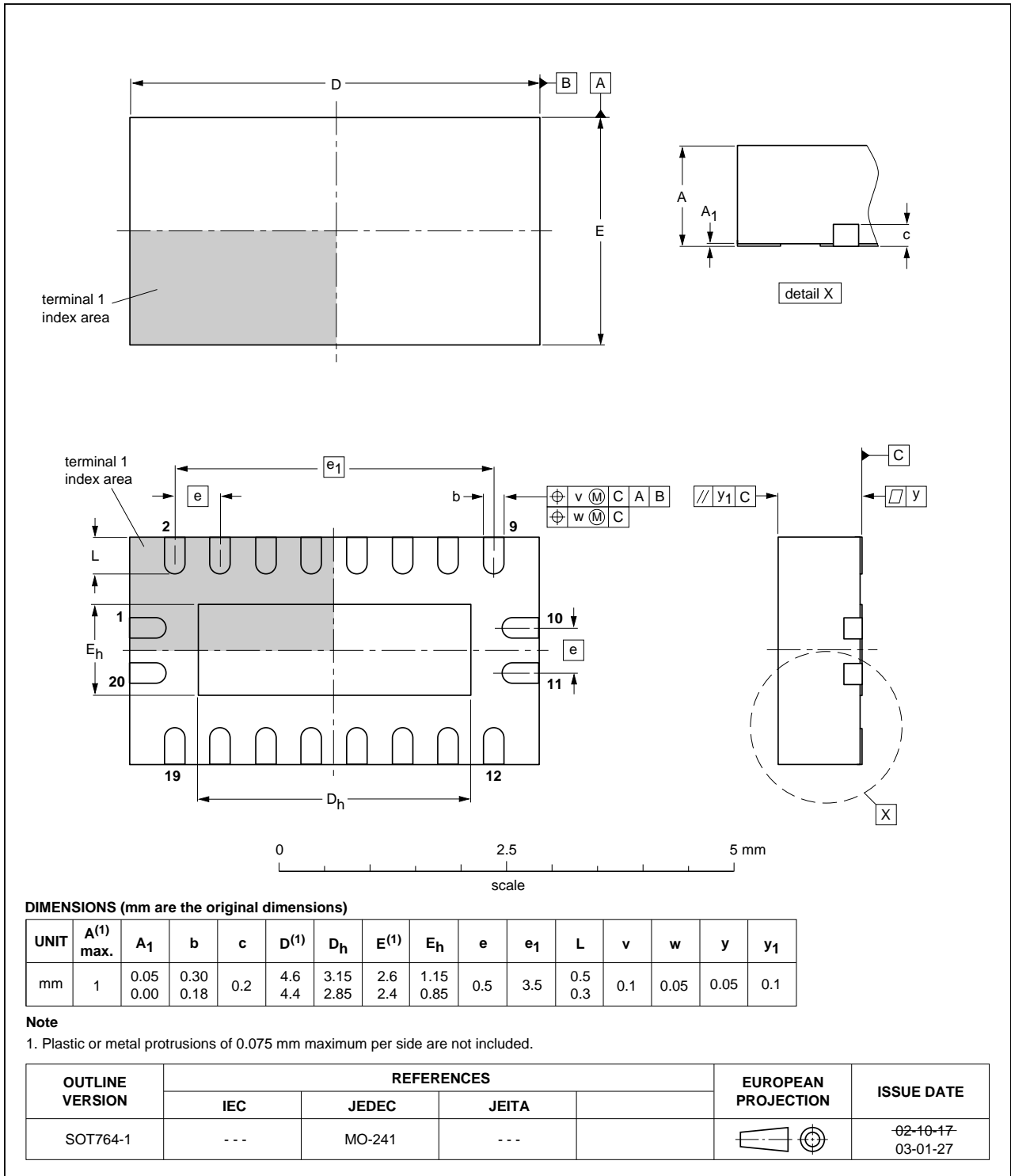


Fig 13. Package outline SOT360-1 (TSSOP20)

**DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm**

**SOT764-1**



**Fig 14. Package outline SOT764-1 (DHVQFN20)**

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT573 v.7	20111108	Product data sheet	-	74AHC_AHCT573 v.6
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74AHC_AHCT573 v.6	20101125	Product data sheet	-	74AHC_AHCT573 v.5
74AHC_AHCT573 v.5	20100325	Product data sheet	-	74AHC_AHCT573 v.4
74AHC_AHCT573 v.4	20100303	Product data sheet	-	74AHC_AHCT573 v.3
74AHC_AHCT573 v.3	20080424	Product data sheet	-	74AHC_AHCT573 v.2
74AHC_AHCT573 v.2	20031208	Product specification	-	74AHC_AHCT573 v.1
74AHC_AHCT573 v.1	19990927	Product specification	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## 17. Contents

<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>
<b>3</b>	<b>Ordering information</b> .....	<b>2</b>
<b>4</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>5</b>	<b>Pinning information</b> .....	<b>4</b>
5.1	Pinning .....	4
5.2	Pin description .....	4
<b>6</b>	<b>Functional description</b> .....	<b>5</b>
<b>7</b>	<b>Limiting values</b> .....	<b>5</b>
<b>8</b>	<b>Recommended operating conditions</b> .....	<b>6</b>
<b>9</b>	<b>Static characteristics</b> .....	<b>6</b>
<b>10</b>	<b>Dynamic characteristics</b> .....	<b>8</b>
<b>11</b>	<b>Waveforms</b> .....	<b>10</b>
<b>12</b>	<b>Package outline</b> .....	<b>13</b>
<b>13</b>	<b>Abbreviations</b> .....	<b>16</b>
<b>14</b>	<b>Revision history</b> .....	<b>16</b>
<b>15</b>	<b>Legal information</b> .....	<b>17</b>
15.1	Data sheet status .....	17
15.2	Definitions .....	17
15.3	Disclaimers .....	17
15.4	Trademarks .....	18
<b>16</b>	<b>Contact information</b> .....	<b>18</b>
<b>17</b>	<b>Contents</b> .....	<b>19</b>

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